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Product Change Notification - KSRA-07JMKW160

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Date:

10 Aug 2018

Product Category:

8-bit Microcontrollers; 16-Bit - Microcontrollers and Digital Signal Controllers; 32-bit Microcontrollers

Affected CPNs:**Notification subject:**

CCB 3499 Initial Notice: Qualification of MMT as an additional assembly site for selected products of 0.25um, 0.18um, 90nm TSMC and 200K wafer technology available in 100L TQFP (14x14x1 mm) package.

Notification text:**PCN Status:**

Initial notification

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change: Qualification of MMT as an additional assembly site for selected products of 0.25um, 0.18um, 90nm TSMC and 200K wafer technology available in 100L TQFP (14x14x1mm) package

Pre Change:

Assembled at ASAC using gold (Au) bond wire, 2200 die attach, G700 molding compound and C7025 lead frame material. Assembled at ANAP using gold (Au) bond wire, 3230 die attach, G700 molding compound and C194 lead frame material. Assembled at ASE using palladium coated copper (PdCu) bond wire, 1076WA die attach, G631H molding compound and C7025 lead frame material.

Post Change:

Assembled at ASAC using gold (Au) bond wire, 2200 die attach, G700 molding compound and C7025 lead frame material. Assembled at ANAP using gold (Au) bond wire, 3230 die attach,

G700 molding compound and C194 lead frame material. Assembled at ASE using palladium coated copper (PdCu) bond wire, 1076WA die attach, G631H molding compound and C7025 lead frame material. Assembled at MMT using gold (Au) bond wire, 3280 die attach, G700 molding compound and C7025 lead frame material.

Pre and Post Change Summary:

	Pre Change			Post Change			
Assembly Site	UTAC Dongguan Ltd (P1) / ASAC	Amkor Technology Philippine (P1/P2), INC. / ANAP	ASE Inc. / ASE	UTAC Dongguan Ltd (P1) / ASAC	Amkor Technology Philippine (P1/P2), INC. / ANAP	ASE Inc. / ASE	Microchip Technology Thailand (Branch) / MMT
Wire material	Au	Au	PdCu	Au	Au	PdCu	Au
Die attach material	2200	3230	1076WA	2200	3230	1076WA	3280
Molding compound material	G700	G700	G631H	G700	G700	G631H	G700
Lead frame material	C7025	C194	C7025	C7025	C194	C7025	C7025
MSL	L3/260C	L3/260C	L3/260C	L3/260C	L3/260C	L3/260C	L1/260C or L2/260C

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve on-time delivery performance by qualifying MMT as a new assembly site.

Change Implementation Status:

In Progress

Estimated Qualification Completion Date:

November 2018

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in

the final PCN customers may receive pre and post change parts.

Time Table Summary:

	August 2018					-->	November 2018			
Workweek	31	32	33	34	35		45	46	47	48
Initial PCN Issue Date		X								
Qual Report Availability								X		
Final PCN Issue Date								X		

Method to Identify Change:

Traceability code

Qualification Plan:

Please open the attachments included with this PCN labeled as PCN_#_Qual Plan.

Revision History:

August 10, 2018: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

[PCN_KSRA-07JMKW160_Qual_Plan.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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